

TrenchT2™ GigaMOS™

MMIX1T550N055T2

Power MOSFET

(Electrically Isolated Tab)

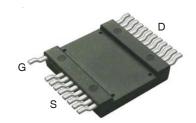
N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode



Symbol	Test Conditions	Maximum Ra	Ratings			
V _{DSS}	$T_{_{\rm J}}$ = 25°C to 175°C	55	V			
V _{DGR}	$T_J = 25^{\circ}C$ to 175°C, $R_{GS} = 1M\Omega$	55	V			
V _{GSM}	Transient	±20	V			
I _{D25}	T _C = 25°C (Chip Capability)	550	А			
I _{DM}	$T_{\rm C} = 25^{\circ}$ C, Pulse Width Limited by $T_{\rm JM}$	2000	Α			
I _A	$T_{c} = 25^{\circ}C$	200	Α			
E _{AS}	$T_{c} = 25^{\circ}C$	3	J			
$P_{_{\rm D}}$	$T_{c} = 25^{\circ}C$	830	W			
T _J		-55 +175	°C			
T _{JM}		175	°C			
T _{stg}		-55 +175	°C			
T _L	1.6mm (0.062 in.) from Case for 10s	300	°C			
T _{SOLD}	Plastic Body for 10s	260	°C			
V _{ISOL}	50/60 Hz, 1 Minute	2500	V~			
F _c	Mounting Force	50200 / 1145	N/lb.			
Weight		8	g			

Symbol	Test Conditions	Characteristic Values		;	
$(T_J = 25^{\circ}C)$	C, Unless Otherwise Specified)	Min.	Тур.	Max	
BV _{DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	55			V
V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	1.8		3.8	V
I _{gss}	$V_{GS} = \pm 20V, V_{DS} = 0V$			±200	nA
I _{DSS}	$V_{DS} = V_{DSS}, V_{GS} = 0V$			10	μΑ
	$T_J = 15$	0°C		1.5	mΑ
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 100A, Note 1$			1.3	mΩ

 $V_{DSS} = 55V$ $I_{D25} = 550A$ $R_{DS(on)} \le 1.3m\Omega$





G = Gate D = Drain S = Source

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Substrate
- Excellent Thermal Transfer
- Increased Temperature and Power Cycling Capability
- High Isolation Voltage (2500V~)
- 175°C Operating Temperature
- Very High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Very Low R_{DS(on)}

Advantages

- Easy to Mount
- Space Savings
- High Power Density

Applications

- DC-DC Converters and Off-Line UPS
- Primary-Side Switch
- High Speed Power Switching Applications



Symbol	Test Conditions	Chara	acteristic	Values
$(T_J = 25^{\circ}C$, Unless Otherwise Specified)	Min.	Тур.	Max.
\mathbf{g}_{fs}	$V_{DS} = 10V, I_{D} = 60A, \text{ Note } 1$	90	150	S
C _{iss}			40	nF
C _{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		4970	pF
C _{rss}			1020	pF
R _{GI}	Gate Input Resistance		1.36	Ω
t _{d(on)}	Resistive Switching Times		45	ns
t _r	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 200A$		40	ns
$\mathbf{t}_{d(off)}$	$R_{G} = 10^{\circ}$, $V_{DS} = 0.00^{\circ}$ V_{DSS} , $V_{D} = 200$, V_{DSS}		90	ns
t _f	· ,		230	ns
Q _{g(on)}			595	nC
\mathbf{Q}_{gs}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{DSS}$		150	nC
Q_{gd}			163	nC
R _{thJC}				0.18 °C/W
\mathbf{R}_{thCS}			0.05	°C/W

Source-Drain Diode

Symbol (T. = 25°C. U		hara in.	cteristic	Value Max.	
I _s	$V_{GS} = 0V$		- 7	550	
I _{SM}	Repetitive, Pulse Width Limited by T _{JM}			1700	Α
V _{SD}	$I_{\rm F} = 100 {\rm A}, V_{\rm GS} = 0 {\rm V}, {\rm Note} 1$			1.2	V
t _{rr}	$I_{\rm F} = 100 {\rm A}, \ V_{\rm GS} = 0 {\rm V}$ $-{\rm di}/{\rm dt} = 100 {\rm A}/{\rm \mu s}$ $V_{\rm R} = 27.5 {\rm V}$		100 5 250		ns A nC

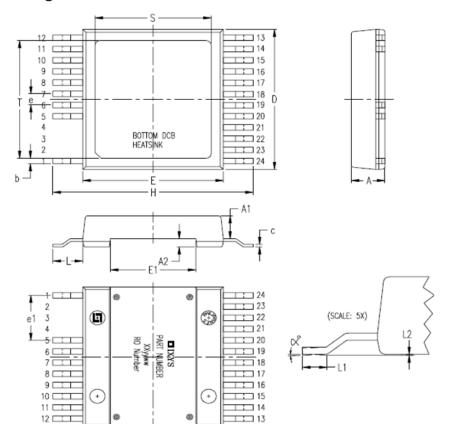
Note 1. Pulse test, $t \le 300 \mu s$, duty cycle, $d \le 2\%$.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.



Package Outline



MYZ	INC	HES	MILLIMETERS	
2114	MIN	MAX	MIN	MAX
Α	.209	.224	5.30	5.70
A1	.154	.161	3.90	4.10
A2	.055	.063	1.40	1.60
b	.035	.045	0.90	1.15
С	.018	.026	0.45	0.65
D	.976	.994	24.80	25.25
E	.898	.915	22.80	23,25
E1	.543	.559	13.80	14.20
е	.079 BSC		2.00 BSC	
e1	.315 BSC		8.00 BSC	
Н	1.272	1.311	32,30	33,30
L	.181	.209	4.60	5.30
L1	.051	.067	1.30	1.70
L2	.000	.006	0.00	0.15
S	.736	.760	18.70	19.30
Т	.815	.839	20.70	21.30
X	0	4*	0	4*

PIN: 1 = Gate 5-12 = Source 13-24 = Drain

